

MATERIAL DATA SHEET

Material #	CDSUR & CDSU series (0603) (Halogen Free)	
Product Line	SOD-523F	
Date	2012/2/20	
Rev.	F	

COMPONENT DETAILS

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	FR-4 Board	Substrate/ Terminal	1.357	Copper	7440-50-8	10~30%	41.45	
				Epoxy Resin	67-64-1	30~60%		
				Fillers	19287-45-7	10~20%		
				E-Glass Fabric	14808-60-7	30~60%		
2	Wafer	Diode	0.029	Silicon	7440-21-3	90.40%	0.89	
				Aluminum	7429-90-5	0.10%		
				Gold	7440-57-5	9.50%		
3	Al wire	Conductor	0.001	Aluminum	7429-90-5	99.00%	0.03	
				Silicon	7440-21-3	<1%		
4	Silver paste	Welding	0.006	Modified Epoxy Resin	29690-82-2	5~25%	0.18	
				Silver	7440-22-4	76~85%		
				Imidazole	827-43-0	1~4%		
				Amide	461-58-5	1~4%		
5	Molding Compound	Outer	1.881	Silica	60676-86-0	70~90%	57.45	
				Epoxy Resin	29690-82-2	6~16%		
				Phenolic Resin	9003-35-4	5~15%		
				Carbon Black	1333-86-4	0.1~1%		
Total weight			3.274					